# PE 1000 - MD

**Material Information** 



## PE 1000 - MD

#### Product full identity:

Polyethylene - Metal Detectable Ultra High Molecular Weight

PE 1000 MD is designed for metal detection in food processing and packaging. With excellent impact strength, wear resistance, chemical resistance, and low moisture absorption, it is fully food compliant and ideal for scanning equipment, food processing, and packaging systems.

### **Properties**

- Metal detectable
- Excellent wear resistance and sliding properties
- High impact strength
- Wide temperature range (+80 to -200°C)
- Low coefficient of friction
- Very low moisture absorption
- Food contact approved

### **Applications**

- Scanning equipment
- Food processing
- Packaging

#### **Forms**



Solid Rod



Sheet

# PE 1000 - MD

## **Technical Properties**

Physical	Unit	Test Method	Result
Specific gravity	g/cm³	ISO 1183-1	1.07
Water absorption until saturation at 23°C	%	ISO 62	<0.1
Maximum service temp. Upper temp limit – short term	°C	-	-
Maximum service temp. Upper temp limit – long term	°C	-	80
Lower temp limit	°C	-	-150
Mechanical	Unit	Test Method	Result
Tensile strength	MPa	ISO 527-1/-2	20
Elongation at yield	%	ISO 527-1/-2	17
Tensile strength at break	MPa	ISO 527-1/-2	>50
Unnotched impact strength	kJ/m²	ISO 179-1/1eU	No break
Notch impact strength	kJ/m²	ISO 179-1/1eA	107P
Ball indentation / Rockwell hardness	MPa	-	-
Shore-D		ISO 868	62
Flexural modulus of elasticity	MPa	ISO 178	660
Tensile modulus of elasticity	MPa	ISO 527-1/-2	670
Thermal	Unit	Test Method	Result
Vicat-softening point VST/B/50	°C	-	-
Heat deflection temperature HDT/B	°C	ISO 75-1/-2	40
Coefficient of linear thermal expansion 23 - 100°C	m/(m.K)	_	230
Coefficient of linear thermal expansion 25 - 100 C	, (		
Thermal conductivity at 23°C	W/mK	-	-
		- Test Method	Result
Thermal conductivity at 23°C	W/mK	- Test Method	
Thermal conductivity at 23°C  Electrical	W/mK Unit	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity	W/mK Unit Ω x m	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity	W/mK Unit Ω x m Ω	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity	W/mK Unit Ω x m Ω	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz	W/mK Unit Ω x m Ω	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz	W/mK Unit Ωxm Ω Ω.cm	Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength	W/mK Unit Ωxm Ω Ω.cm	Test Method  Test Method	
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)	W/mK Unit Ω x m Ω Ω . cm		- Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)	W/mK Unit Ω x m Ω Ω . cm		Result  -  -  -  -  -  -  -  -  -  -  -  -  -
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability	W/mK Unit Ω x m Ω Ω . cm	Test Method	Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability  Food compliance – FDA	W/mK Unit Ω x m Ω Ω . cm	Test Method - FDA	Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability  Food compliance – FDA  Food compliance – EU	W/mK Unit Ω x m Ω Ω . cm	Test Method - FDA	Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability  Food compliance – FDA  Food compliance – EU  Antistatic	W/mK Unit Ω x m Ω Ω . cm kV/mm		- Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability  Food compliance – FDA  Food compliance – EU  Antistatic  Flammability  Fire performance	W/mK Unit Ω x m Ω Ω . cm  kV/mm Unit		- Result
Thermal conductivity at 23°C  Electrical  Volume resistivity  Surface resistivity  Insulation resistivity  Dielectric constant at 1MHz  Dielectric loss factor at 1MHz  Dielectric strength  Comparative tracking index (CTI)  Additional Data  Bondability  Food compliance – FDA  Food compliance – EU  Antistatic  Flammability	W/mK Unit Ω x m Ω Ω . cm kV/mm		- Result

All information provided in this Product Datasheet is for guide purposes only. The data has been taken from standard test results provided by our manufacturers.